

Voltage Detector with External Delay Type Capacitor

GENERAL DESCRIPTION

The XC6109 series is highly precise, low power consumption voltage detector, manufactured using CMOS and laser trimming technologies.

With the built-in delay circuit, connecting the delay capacitance pin to the capacitor enables the IC to provide an arbitrary release delay time.

Using an ultra small package (SSOT-24), the series is suited for high density mounting.

Both CMOS and N-channel open drain output configurations are available.

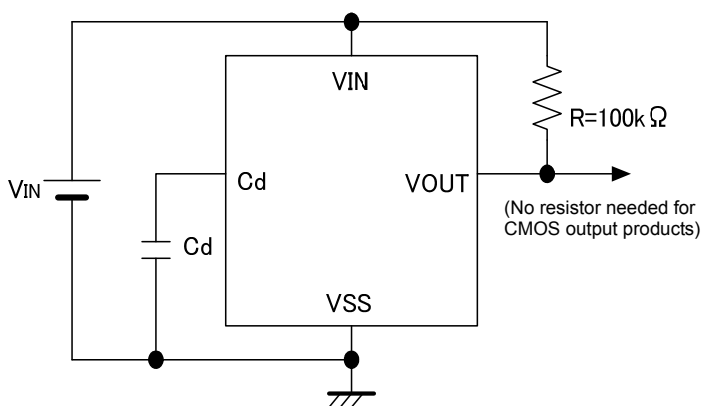
APPLICATIONS

- Microprocessor reset circuitry
- Charge voltage monitors
- Memory battery back-up switch circuits
- Power failure detection circuits

FEATURES

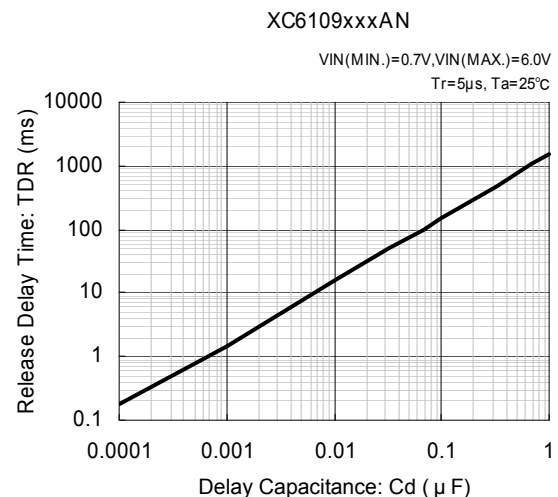
- Highly Accurate** : $\pm 2\%$
(Setting Voltage Accuracy $\geq 1.5V$)
: $\pm 30mV$
(Setting Voltage Accuracy $< 1.5V$)
- Low Power Consumption** : $0.9 \mu A$
(TYP., $V_{DF}=1.9V$, $V_{IN}=2.0V$)
- Detect Voltage Range** : $0.8V \sim 5.0V$
in $100mV$ increments
- Operating Voltage Range** : $0.7V \sim 6.0V$
- Detect Voltage Temperature Characteristics**
: $\pm 100ppm/^{\circ}C$ (TYP.)
- Output Configuration** : CMOS or
N-channel open drain
- Operating Temperature Range** : $-40^{\circ}C \sim +85^{\circ}C$
- CMOS**
- Built-In Delay Circuit, Delay Pin Available**
- Ultra Small Package** : SSOT-24

TYPICAL APPLICATION CIRCUIT

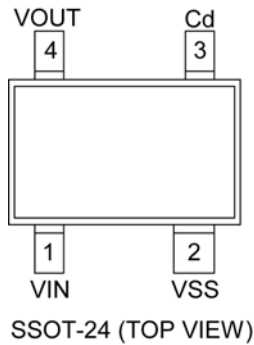


TYPICAL PERFORMANCE CHARACTERISTICS

Release Delay Time vs. Delay Capacitance



PIN CONFIGURATION



PIN ASSIGNMENT

PIN NUMBER	PIN NAME	FUNCTION
1	VIN	Input
2	VSS	Ground
3	Cd	Delay Capacitance
4	VOUT	Output (Detect "L")

PRODUCT CLASSIFICATION

Ordering Information

XC6109

DESIGNATOR	DESCRIPTION	SYMBOL	DESCRIPTION
	Output Configuration	C	: CMOS output
		N	: N-ch open drain output
	Detect Voltage	08 ~ 50	: e.g. 18 1.8V
	Output Delay & Hysteresis	A	: Built-in delay pin & hysteresis 5% (TYP.)
	Package	N	: SSOT-24
	Device Orientation	R	: Embossed tape, standard feed
		L	: Embossed tape, reverse feed

ELECTRICAL CHARACTERISTICS

Ta = 25°C

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNIT	CIRCUIT
Operating Voltage	VIN	VDF(T)=0.8~5.0V ^{(*)1}	0.7	-	6.0	V	-
Detect Voltage	VDF	VDF(T)=0.8~5.0V	E-1			V	
Hysteresis Width	VHYS	VIN=1.0~6.0V	VDF x 0.02	VDF x 0.05	VDF x 0.08	V	
Supply Current 1	ISS1	VIN=VDF x 0.9	VDF(T)=0.8~1.9V	-	0.80	1.70	μA
			VDF(T)=2.0~3.9V	-	0.90	1.90	
			VDF(T)=4.0~5.0V	-	1.00	2.00	
Supply Current 2	ISS2	VIN=VDF x 1.1	VDF(T)=0.8~1.9V	-	0.90	1.80	μA
			VDF(T)=2.0~3.9V	-	1.10	2.00	
			VDF(T)=4.0~5.0V	-	1.20	2.20	
Output Current	IOUT1	VIN=0.7V VDS=0.5V(Nch)	0.01	0.36	-	mA	
		VIN=1.0V ^{(*)2} VDS=0.5V(Nch)	0.1	0.7			
		VIN=2.0V ^{(*)3} VDS=0.5V(Nch)	0.8	1.6			
		VIN=3.0V ^{(*)4} VDS=0.5V(Nch)	1.2	2.0			
		VIN=4.0V ^{(*)5} VDS=0.5V(Nch)	1.6	2.3			
	IOUT2 ^{(*)6}	VIN=VDFx1.1 VDS=0.5V (P-ch)	E-2			mA	
Leak Current	CMOS output	I _{LEAK}	VIN=6.0V, VOUT=6.0V, Cd: Open	-	0.20	-	μA
	N-ch Open Drain Output			-	0.20	0.40	
Temperature Characteristics	$\frac{\Delta VDF}{\Delta Ta \cdot VDF}$	-40°C ≤ Ta ≤ 85°C	-	± 100	-	ppm/°C	
Delay Resistance ^{(*)7}	Rdelay	VIN=6.0V, Cd=0V	1.6	2.0	2.4	MΩ	
Delay Pin Sink Current	ICD	Cd=0.5V, VIN=0.7V	8	60	-	μA	
Delay Capacitance Pin Threshold Voltage	VTCD	VIN=1.0V	0.4	0.5	0.6	V	
		VIN=6.0V	2.9	3.0	3.1		
Unspecified Operating Voltage ^{(*)8}	VUNS	VIN=0~0.7V	-	0.3	0.4	V	
Detect Delay Time ^{(*)9}	TDF0	VIN=6.0 down to 0.7V Cd: Open	-	30	230	μs	
Release Delay Time ^{(*)10}	TDR0	VIN=0.7~6.0V Cd: Open	-	30	200	μs	

NOTE:

*1: VDF(T): Setting Detect Voltage

*2: VDF(T) > 1.0V

*3: VDF(T) > 2.0V

*4: VDF(T) > 3.0V

*5: VDF(T) > 4.0V

*6: This numerical value is applied only to the XC6109C series (CMOS output).

*7: Calculated from the voltage value and the current value of both ends of the resistor.

*8: The maximum voltage of the VOUT in the range of the VIN 0 to 0.7V. This numerical value is applied only to the XC6109C series (CMOS output).

*9: Time which ranges from the state of VIN =VDF to the VOUT reaching 0.6V when the VIN falls without connecting to the Cd pin.

*10: Time which ranges from the state of VIN= VDF +VHYS to the VOUT reaching 5.4V when the VIN rises without connecting to the Cd pin.

VOLTAGE CHART

SYMBOL	E-1			E-2	
PARAMETER	DETECT VOLTAGE ^{(*)1} (V)			OUTPUT CURRENT ^{(*)2} (mA)	
SETTING DETECT VOLTAGE	VDF			Iout2	
VDF(T)	MIN.	TYP.	MAX.	MIN.	TYP.
0.8	0.770	0.800	0.830	-0.40	-0.20
0.9	0.870	0.900	0.930		
1.0	0.970	1.000	1.030		
1.1	1.070	1.100	1.130	-0.60	-0.30
1.2	1.170	1.200	1.230		
1.3	1.270	1.300	1.330		
1.4	1.370	1.400	1.430		
1.5	1.470	1.500	1.530		
1.6	1.568	1.600	1.632	-0.80	-0.40
1.7	1.666	1.700	1.734		
1.8	1.764	1.800	1.836		
1.9	1.862	1.900	1.938		
2.0	1.960	2.000	2.040		
2.1	2.058	2.100	2.142	-1.00	-0.50
2.2	2.156	2.200	2.244		
2.3	2.254	2.300	2.346		
2.4	2.352	2.400	2.448		
2.5	2.450	2.500	2.550		
2.6	2.548	2.600	2.652		
2.7	2.646	2.700	2.754		
2.8	2.744	2.800	2.856		
2.9	2.842	2.900	2.958		
3.0	2.940	3.000	3.060		
3.1	3.038	3.100	3.162	-1.20	-0.60
3.2	3.136	3.200	3.264		
3.3	3.234	3.300	3.366		
3.4	3.332	3.400	3.468		
3.5	3.430	3.500	3.570		
3.6	3.528	3.600	3.672		
3.7	3.626	3.700	3.774		
3.8	3.724	3.800	3.876		
3.9	3.822	3.900	3.978		
4.0	3.920	4.000	4.080		
4.1	4.018	4.100	4.182	-1.30	-0.65
4.2	4.116	4.200	4.284		
4.3	4.214	4.300	4.386		
4.4	4.321	4.400	4.488		
4.5	4.410	4.500	4.590		
4.6	4.508	4.600	4.692		
4.7	4.606	4.700	4.794		
4.8	4.704	4.800	4.896		
4.9	4.802	4.900	4.998		
5.0	4.900	5.000	5.100		

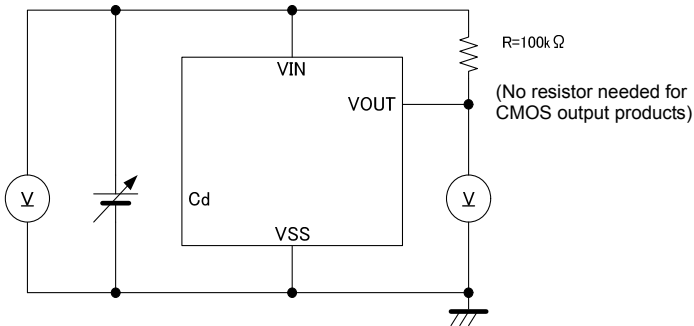
NOTE:

*1: When VDF(T) 1.4V, the detection accuracy is $\pm 30\text{mV}$. When VDF(T) 1.5V, the detection accuracy is $\pm 2\%$.

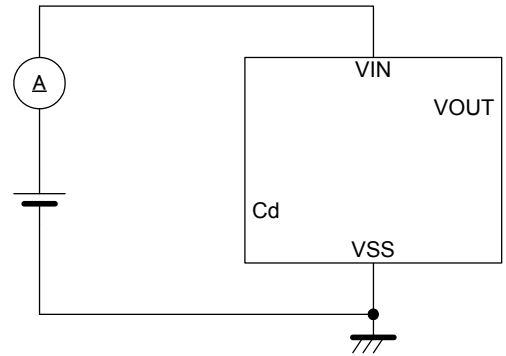
*2: This numerical value is applied only to the XC6109C series (CMOS output).

TEST CIRCUITS

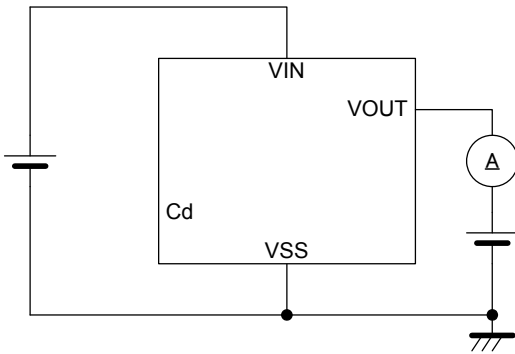
Circuit 1



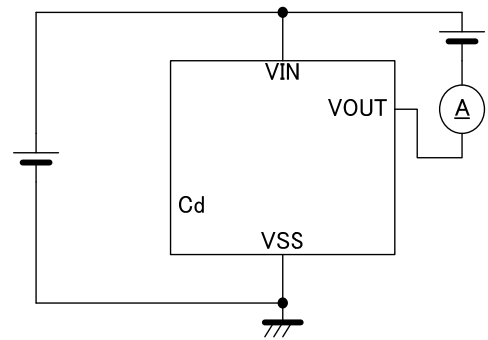
Circuit 2



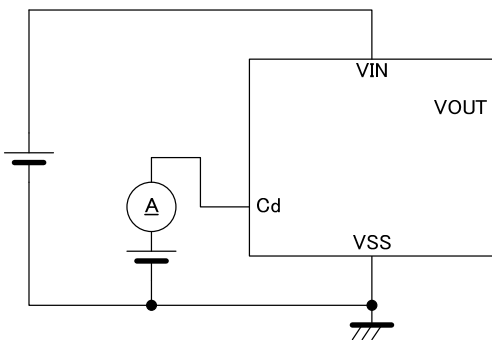
Circuit 3



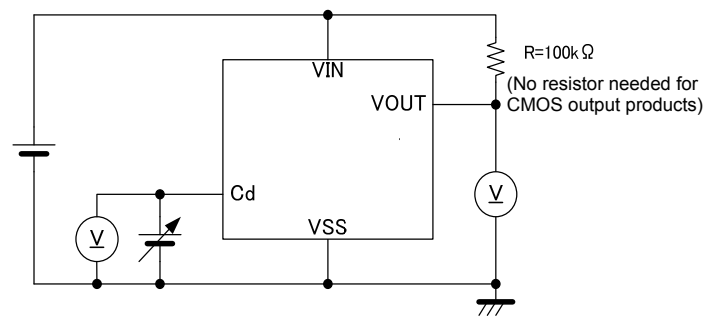
Circuit 4



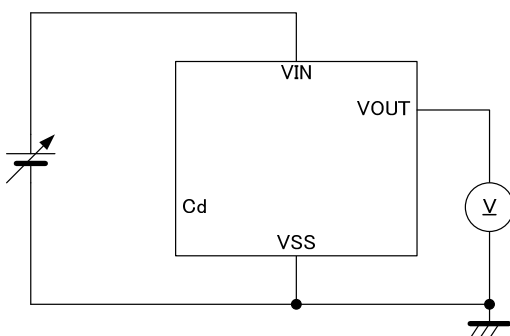
Circuit 5



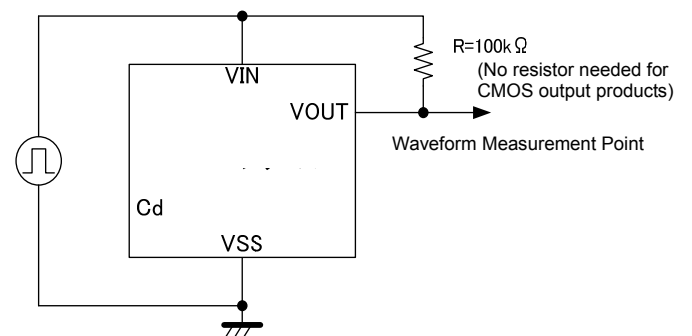
Circuit 6



Circuit 7



Circuit 8



OPERATIONAL EXPLANATION

A typical circuit example is shown in Figure 1, and the timing chart of Figure 1 is shown in Figure 2 on the next page.

As an early state, the input voltage pin is applied sufficiently high voltage to the release voltage and the delay capacitance (Cd) is charged to the input pin voltage. While the input pin voltage (VIN) starts dropping to reach the detect voltage (VDF) (VIN > VDF), the output voltage (VOUT) keeps the "High" level (=VIN).

When the input pin voltage keeps dropping and becomes equal to the detect voltage (VIN = VDF), an N-ch transistor for the delay capacitance discharge is turned ON, and starts to discharge the delay capacitance. For the internal circuit, which uses the delay capacitance pin as power input, the reference voltage operates as a comparator of VIN, and the output voltage changes into the "Low" level (VIN x 0.1). The detect delay time (TDF) is defined as time which ranges from VIN = VDF to the VOUT of "Low" level (especially, when the Cd pin is not connected: TDF0).

While the input pin voltage keeps below the detect voltage, and 0.7V or more, the delay capacitance is discharged to the ground voltage (=VSS) level. Then, the output voltage (VOUT) maintains the "Low" level.

While the input pin voltage drops to 0.7V or less and it increases again to 0.7V or more, the output voltage may not be able to maintain the "Low" level. Such an operation is called "Unspecified Operation", and voltage which occurs at the output pin voltage is defined as unstable operating voltage (VUNS).

While the input pin voltage increases more than 0.7V and it reaches to the release voltage level (VIN < VDF + VHYS), the output voltage (VOUT) maintains the "Low" level.

When the input pin voltage continues to increase more than 0.7V up to the release voltage level (= VDF + VHYS), the N-ch transistor for the delay capacitance discharge will be turned OFF, and the delay capacitance will be started discharging via a delay resistor (Rdelay). The internal circuit, which uses the delay capacitance pin as power input, will operate as a hysteresis comparator (Rise Logic Threshold: VTLH=VTCD, Fall Logic Threshold: VTHL=VSS) while the input pin voltage keeps higher than the detect voltage (VIN > VDF).

While the input pin voltage becomes equal to the release voltage or higher and keeps the detect voltage or higher, the delay capacitance (Cd) will be charged up to the input pin voltage. When the delay capacitance pin voltage (VCD) reaches to the delay capacitance pin threshold voltage (VTCD), the output voltage changes into the "High" (=VIN) level. TDR is defined as time which ranges from VIN = VDF + VHYS to the VOUT of "High" level (especially when the Cd pin is not connected: TDR0). TDR can be given by the formula (1).

$$TDR = -R_{delay} \times Cd \times \ln(1 - VTCD / VIN) + TDR0 \dots(1)$$

* ln = a natural logarithm

The release delay time can also be briefly calculated with the formula (2) because the delay resistance is 2.0M (TYP.) and the delay capacitance pin threshold voltage is VIN / 2 (TYP.)

$$TDR = R_{delay} \times Cd \times 0.69 \dots(2)$$

* Rdelay is 2.0M (TYP.)

As an example, presuming that the delay capacitance is 0.68 μF, TDR is :

$$2.0 \times 10^6 \times 0.68 \times 10^{-6} \times 0.69 = 938(\text{ms})$$

* Note that the release delay time may remarkably be short when the delay capacitance is not discharged to the ground (=VSS) level because time described in is short.

While the input pin voltage is higher than the detect voltage (VIN > VDF), therefore, the output voltage maintains the "High"(=VIN) level.

Release Delay Time Chart

Delay Capacitance [Cd] (μF)	Release Delay Time [TDR] (TYP.) (ms)	Release Delay Time [TDR] (MIN. ~ MAX.) (ms)
0.01	13.8	11.0 ~ 16.6
0.022	30.4	24.3 ~ 36.4
0.047	64.9	51.9 ~ 77.8
0.1	138	110 ~ 166
0.22	304	243 ~ 364
0.47	649	519 ~ 778
1	1380	1100 ~ 1660

OPERATIONAL EXPLANATION (Continued)

Figure 1: Typical application circuit example

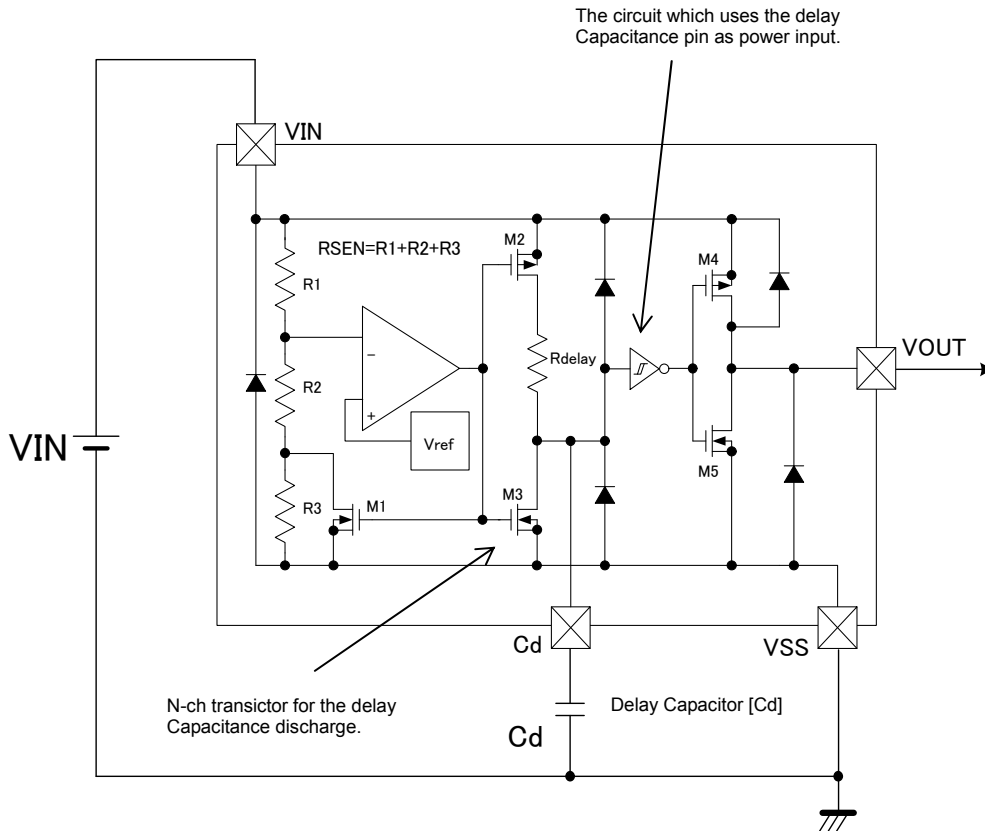
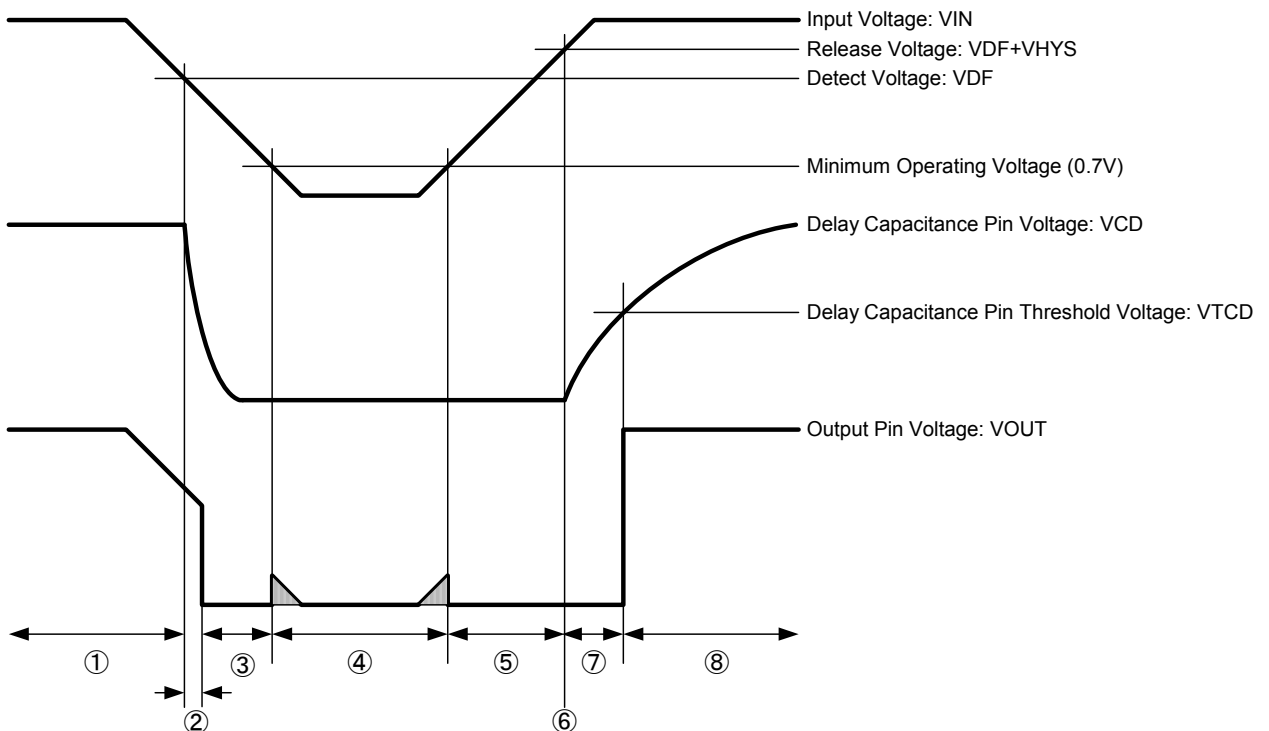


Figure 2: The timing chart of Figure 1



NOTES ON USE

1. Use this IC within the stated maximum ratings. Operation beyond these limits may cause degrading or permanent damage to the device.
2. The input pin voltage drops by the resistance between power supply and the VIN pin, and by through current at operation of the IC. At this time, the operation may be wrong if the input pin voltage falls below the minimum operating voltage range. In CMOS output, for output current, drops in the input pin voltage similarly occur. Oscillation of the circuit may occur if the drops in voltage, which caused by through current at operation of the IC, exceed the hysteresis voltage. Note it especially when you use the IC with the VIN pin connected to a resistor.
3. Note that a rapid and high fluctuation of the input pin voltage may cause a wrong operation.
4. When there is a possibility of which the input pin voltage falls rapidly (e.g.: 6.0V to 0V) at release operation with the delay capacitance pin (Cd) connected to a capacitor, use a schottky barrier diode connected between the VIN pin and the Cd pin as the Figure 3 shown below.
5. When N-ch open drain output is used, output voltages V_{OUT} at voltage detection and release are determined by a pull-up resistor tied to the output pin. A resistance value of the pull-up resistor can be selected with referring to the followings. (Refer to Figure 4)

During detection, the formula is given as

$$V_{OUT} = V_{pull} / (1 + R_{pull} / R_{ON})$$

where V_{pull} is pull-up voltage and R_{ON} (*1) is ON resistance of N-ch driver M5 ($R_{ON} = V_{DS} / I_{OUT1}$ from the electrical characteristics table).

For example, when $V_{IN} = 2.0V$ (*2), $R_{ON} = 0.5 / 0.8 \times 10^{-3} = 625$ (MIN.) and if you want to get V_{OUT} less than 0.1V when $V_{pull} = 3.0V$, R_{pull} can be calculated as follows;

$$R_{pull} = (V_{pull} / V_{OUT} - 1) \times R_{ON} = (3 / 0.1 - 1) \times 625 = 18k$$

Therefore, pull-up resistance should be selected 18k or higher.

(*1) V_{IN} is smaller, R_{ON} is bigger

(*2) For the calculation, the lowest V_{IN} should be used among of the V_{IN} range

During release, the formula is given as

$$V_{OUT} = V_{pull} / (1 + R_{pull} / R_{off})$$

where V_{pull} is pull-up voltage R_{off} is OFF resistance of N-ch driver M5 ($R_{off} = V_{OUT} / I_{LEAK} = 15M$ from the electrical characteristics table)

For examples, if you want to get V_{OUT} larger than 5.99V when V_{pull} is 6.0V, R_{pull} can be calculated as follows;

$$R_{pull} = (V_{pull} / V_{OUT} - 1) \times R_{off} = (6 / 5.99 - 1) \times 15 \times 10^6 = 25k$$

Therefore, pull-up resistance should be selected 25k or below.

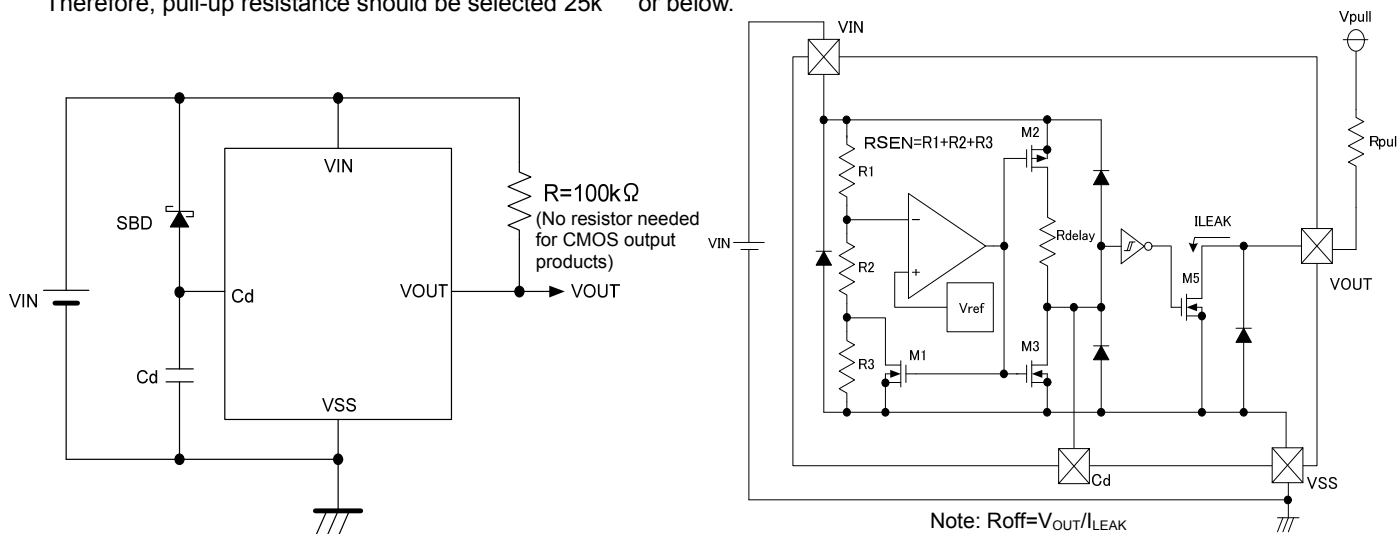


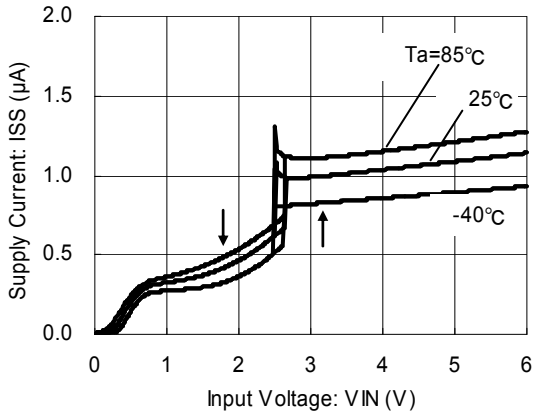
Figure 3: Circuit example with the delay capacitance pin (Cd) connected to a schottky barrier diode

Figure 4: Circuit example of XC6109N Series

TYPICAL PERFORMANCE CHARACTERISTICS

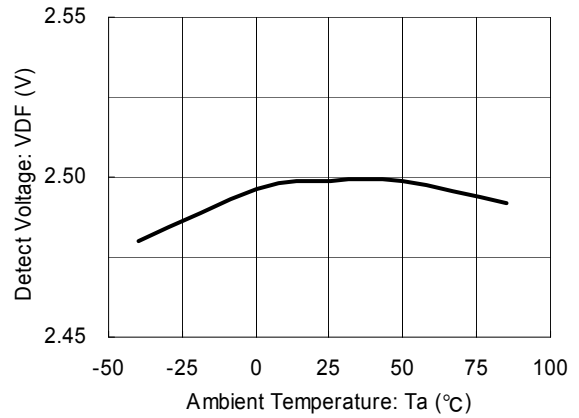
(1) Supply Current vs. Input Voltage

XC6109x25AN



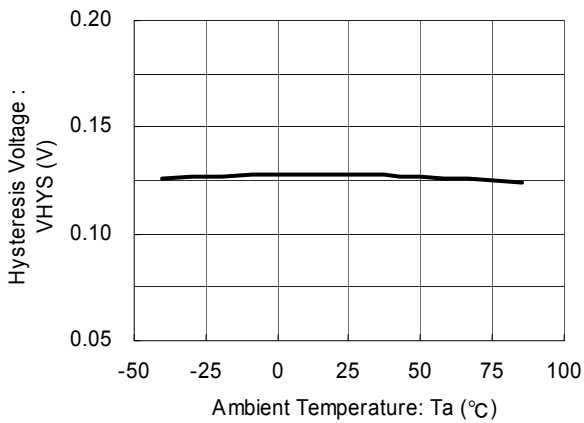
(2) Detect Voltage vs. Ambient Temperature

XC6109x25AN



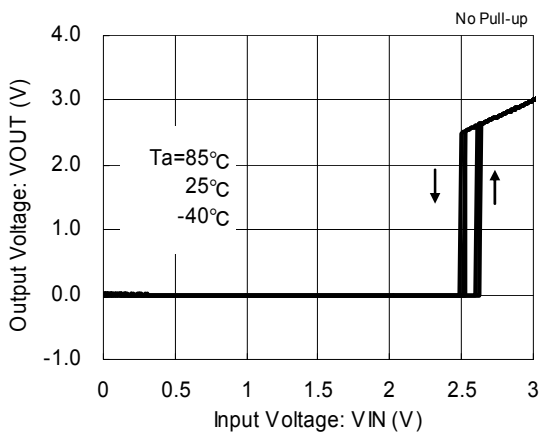
(3) Hysteresis Voltage vs. Ambient Temperature

XC6109x25AN

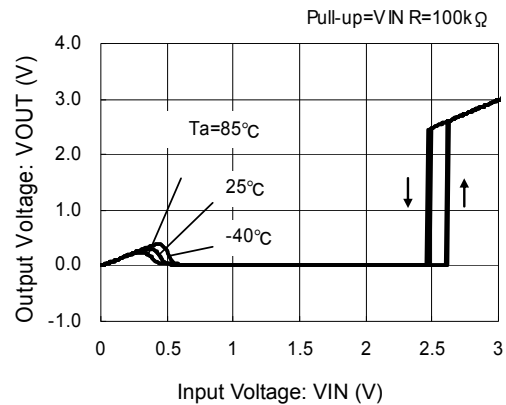


(4) Output Voltage vs. Input Voltage

XC6109C25AN

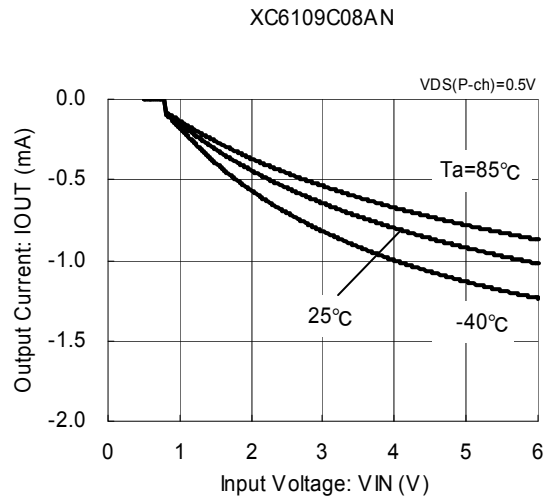
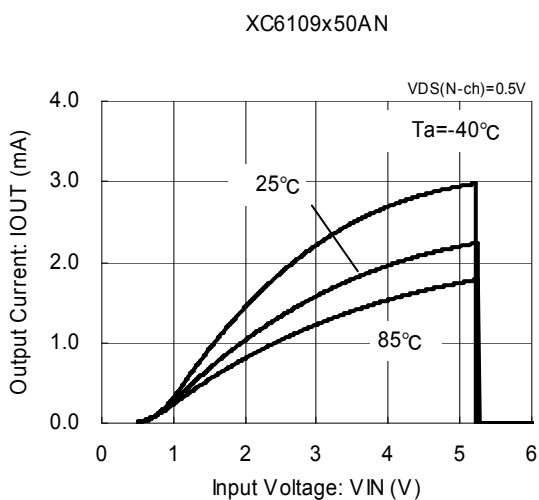


XC6109N25AN

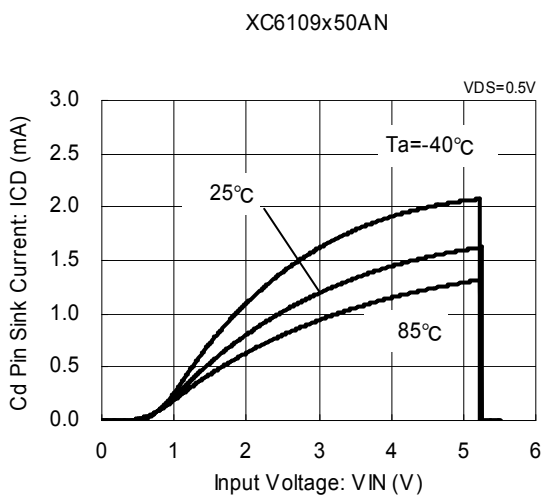


TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

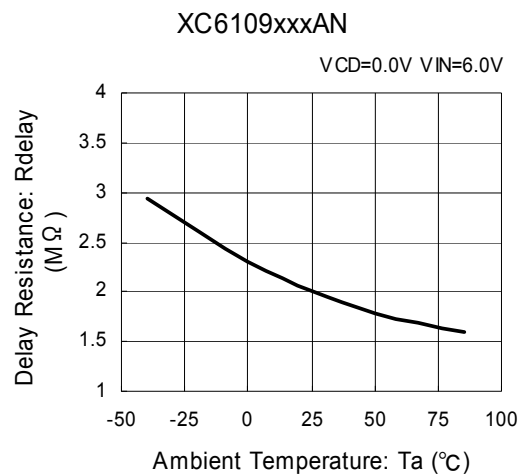
(5) Output Current vs. Input Voltage



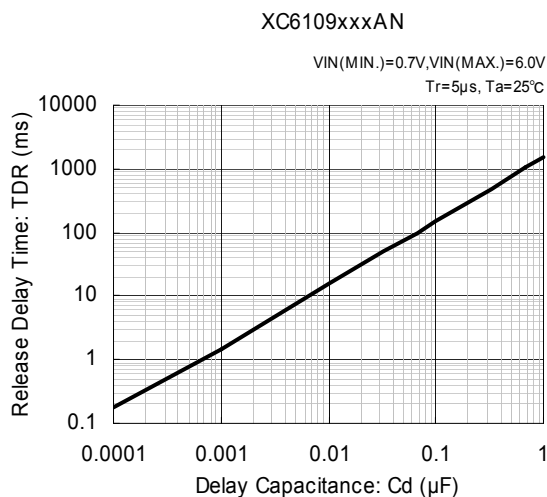
(6) Cd Pin Sink Current vs. Input Voltage



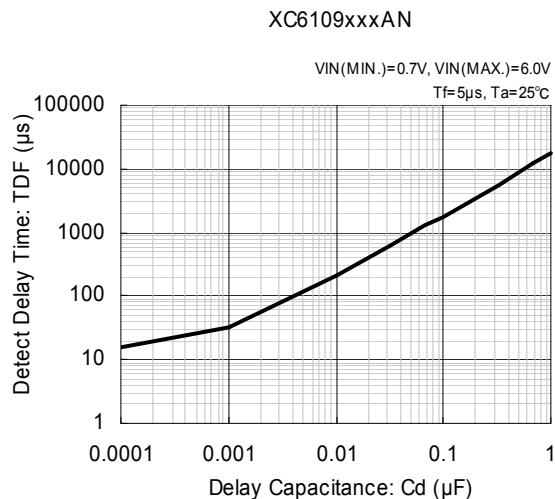
(7) Delay Resistance vs. Ambient Temperature



(8) Release Delay Time vs. Delay Capacitance

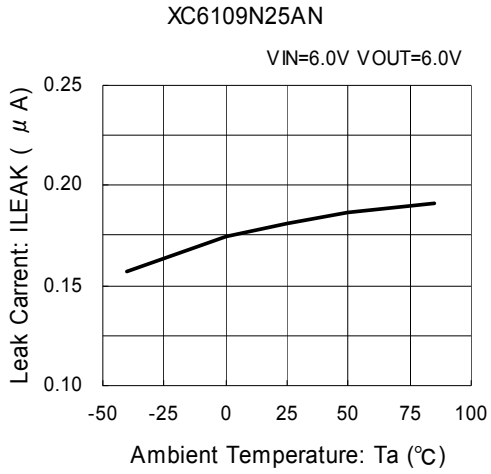


(9) Detect Delay Time vs. Delay Capacitance

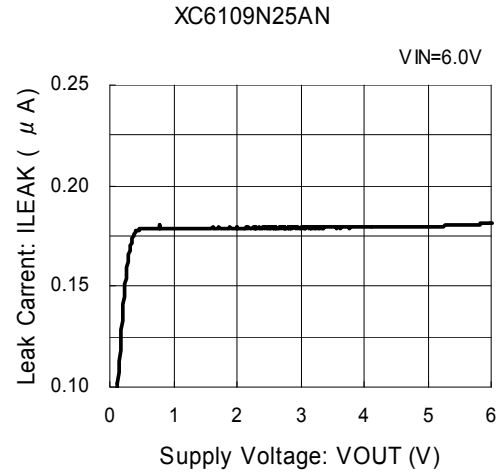


TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(10) Leak Current vs. Ambient Temperature

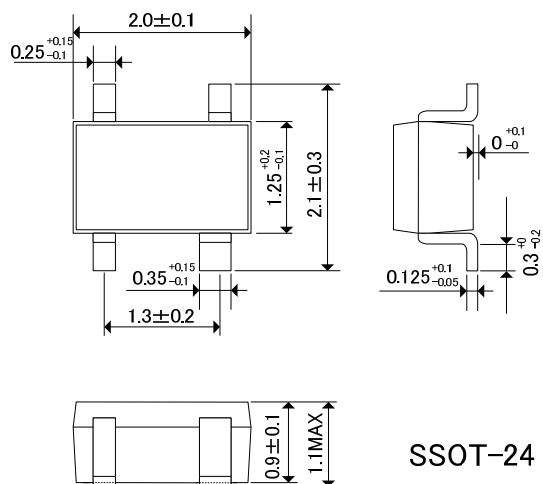


(11) Leak Current vs. Supply Voltage



PACKAGING INFORMATION

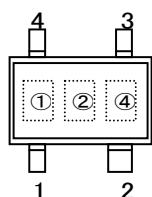
SSOT-24
(unit : mm)



SSOT-24 Package

MARKING RULE

SSOT-24



SSOT-24
(TOP VIEW)

Represents output configuration and integer number of detect voltage
CMOS output (XC6109C Series) N-ch Open Drain output (XC6109N Series)

MARK	VOLTAGE (V)	PRODUCT SERIES	MARK	VOLTAGE (V)	PRODUCT SERIES
A	0.x	XC6109C0xxNx	K	0.x	XC6109N0xxNx
B	1.x	XC6109C1xxNx	L	1.x	XC6109N1xxNx
C	2.x	XC6109C2xxNx	M	2.x	XC6109N2xxNx
D	3.x	XC6109C3xxNx	N	3.x	XC6109N3xxNx
E	4.x	XC6109C4xxNx	P	4.x	XC6109N4xxNx
F	5.x	XC6109C5xxNx	R	5.x	XC6109N5xxNx

Represents decimal number of detect voltage

MARK	VOLTAGE (V)	PRODUCT SERIES
N	x.0	XC6109xx0xNx
P	x.1	XC6109xx1xNx
R	x.2	XC6109xx2xNx
S	x.3	XC6109xx3xNx
T	x.4	XC6109xx4xNx
U	x.5	XC6109xx5xNx
V	x.6	XC6109xx6xNx
X	x.7	XC6109xx7xNx
Y	x.8	XC6109xx8xNx
Z	x.9	XC6109xx9xNx

Represents production lot number

0 to 9, A to Z or inverted characters of 0 to 9, A to Z repeated/
(G, I, J, O, Q, W excepted)

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